



## Surface mount zener diode

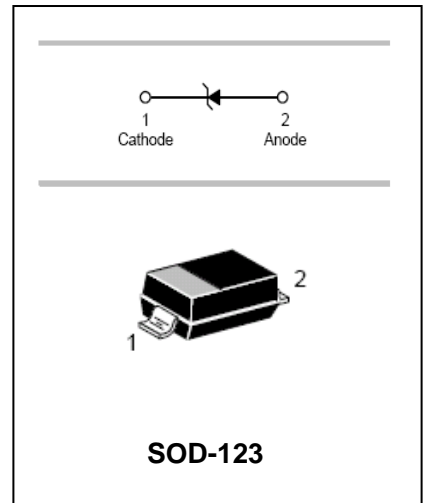
## UMDA5.6

### FEATURES

- Planar die construction.
- 500mW power dissipation on ceramic PCB.
- General purpose, medium current.
- Ideally suited for automated assembly processes.



Lead-free



### APPLICATIONS

- Zener diode.
- Ultra-small surface mount package.

### ORDERING INFORMATION

Type No.	Marking	Package Code
UMDA5.6	WA	SOD-123

### MAXIMUM RATING @ Ta=25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward Voltage @ I <sub>F</sub> =10mA	V <sub>F</sub>	0.9	V
Power Dissipation	P <sub>d</sub>	500	mW
Thermal resistance, junction to ambient air	R <sub>θjA</sub>	305	°C/W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C

Notes: 1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm<sup>2</sup>

2. Short duration test pulse used to minimize self-heating effect.

3. When provided, otherwise, parts are provided with date code only, and type number identifications appears on reel only.

4. f = 1KHz



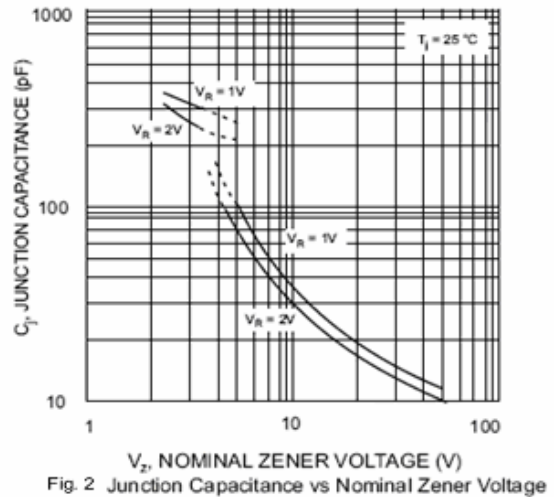
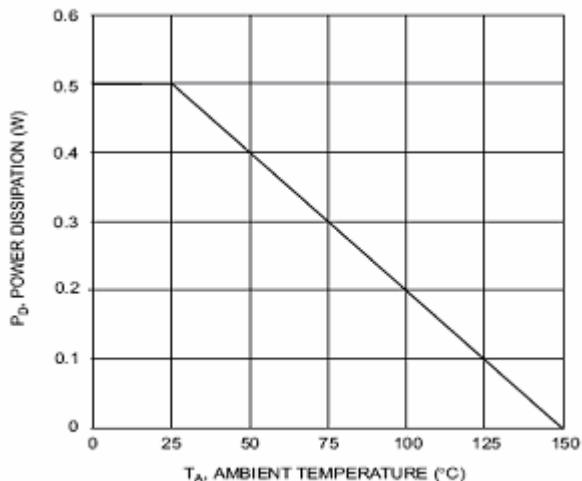
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ELECTRICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

Type Number	Marking Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current		Typical Temperature Coefficient@ I <sub>ZTC</sub> mV/°C		Test Current I <sub>ZTC</sub> mA
		V <sub>Z</sub> @I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	@V <sub>R</sub>	I <sub>ZTC</sub> mV/°C		
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	μA	V	Min	Max	
UMDA5.6	WA	6.2	5.8	6.6	5	10	150	1.0	3.0	4.0	0.4	3.7	5

TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified



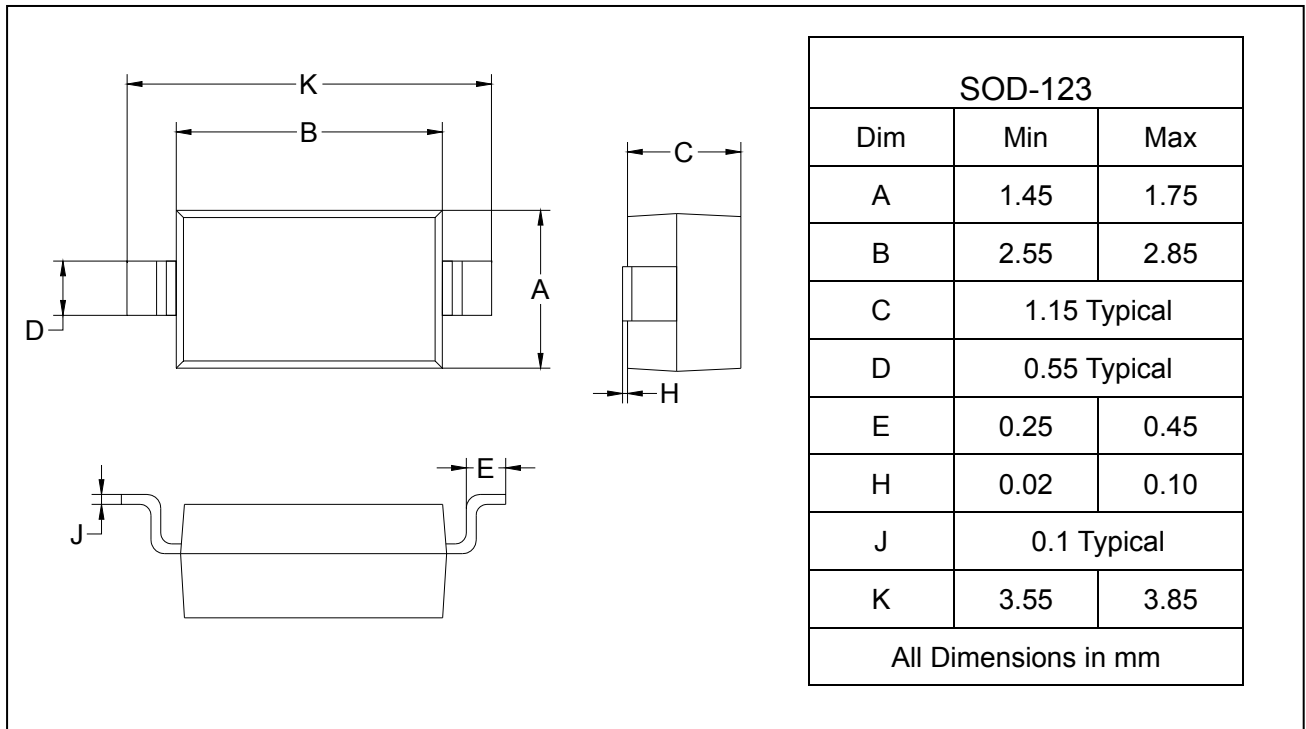
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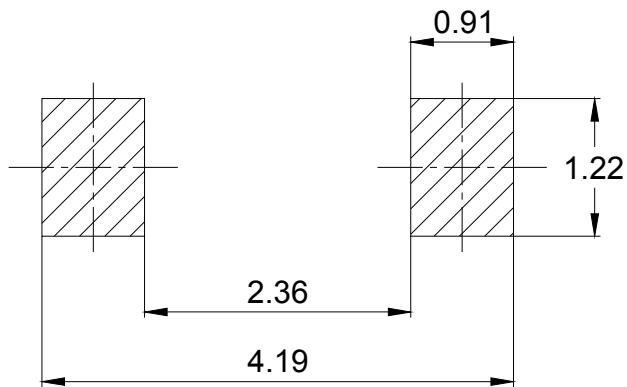
### PACKAGE OUTLINE

Plastic surface mounted package

SOD-123



### SOLDERING FOOTPRINT



Unit: mm

### PACKAGE INFORMATION

Device	Package	Shipping
UMDA5.6	SOD-123	3000/Tape&Reel